

Title (en)

ACID BATH FOR THE GALVANIC DEPOSITION OF COPPER, AND THE USE OF SUCH A BATH

Title (de)

SAURES BAD ZUR GALVANISCHEN ABSCHIEDUNG VON KUPFER UND DESSEN VERWENDUNG

Title (fr)

BAIN ACIDE DE DEPOT GALVANIQUE DE CUIVRE ET SON UTILISATION

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Application

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Abstract (en)

[origin: US5433840A] PCT No. PCT/DE92/00605 Sec. 371 Date Apr. 6, 1994 Sec. 102(e) Date Apr. 6, 1994 PCT Filed Jul. 22, 1992 PCT Pub. No. WO93/03204 PCT Pub. Date Feb. 18, 1993. An aqueous acid bath for the galvanic deposition of bright, ductile and smooth copper coats which is suitable for decorative purposes as well as for strengthening the conductors of printed circuits. The bath is characterized by a content of polyalkylene glycol ether. When combined with thio compounds containing water-soluble groups, these additions produce an electrolyte with excellent stability. Polymeric phenazonium compounds, polymeric nitrogen compounds and/or thio compounds containing nitrogen may also be successfully combined, in addition, depending on the desired properties.

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